

August 10th, 2004

PCN 0204

Product change notification TDC-F1

Dear customer,

We want to inform you that, in compliance with the EU directives WEEE and RHS, we will switch this device from a Non-Pb-free PQFP 160 package to a Pb-free PQFP 160 package from September/October this year 2004. This change can be followed up by a dedicated datecode.

The plating material will be Sn.

For reflow soldering the new package fullfills the following conditions:

Average ramp-up rate (T_L to T_p)	3 °C/second max
Preheat - Temperature min (T_{smin}) - Temperature max (T_{smax}) - Time (min to max) (t_s)	150 °C 200 °C 60 - 120 seconds
T_{smax} to T_L - Ramp-up rate	1.5 - 2.5 °C/second max
Time maintained above - Temperature (T_L) - Time (t_L)	217 °C 60 - 150 seconds
Peak temperature (T_p)	260 +0/-5 °C
Time within 5 °C of actual Peak	20 - 40 seconds
Ramp-down rate	6 °C/second max.
Time 25 °C to Peak temperature	8 minutes max.

This change doesn't affect the electrical behavior and quality of the product in any way.
This change doesn't affect the mechanical outline dimensions of the package.

With kind regards,
acam-messelectronic gmbh

Norbert Breyer
Marketing